

S2088BO-II

Economical AOI solution

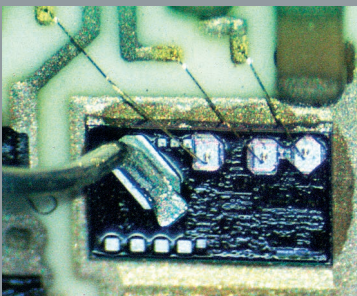
**Precise, reliable inspection
down to 17 µm wire diameters**

Wide inspection scope

**Very simple inspection
program generation**

**Completely compatible with
Viscom inline systems**

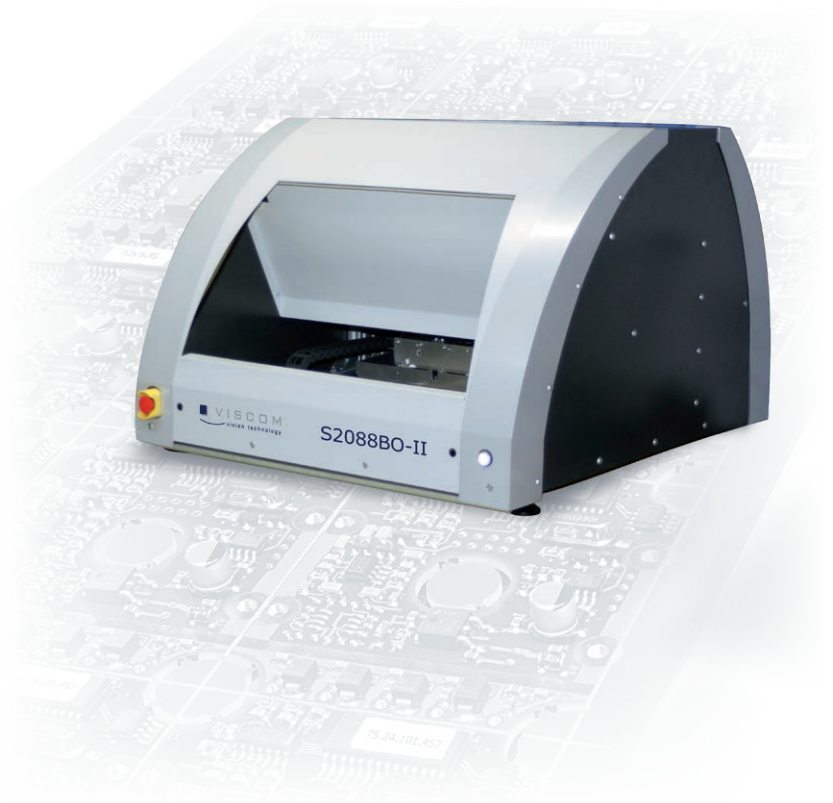
**Additional advantages as
programming station**



**Defect detection on bond
wires of different diameters**



**Defect detection on
multiple wire connections
and multiple loops**



Reliable wirebond control with desktop AOI

This compact AOI system was developed to inspect medium and small product runs. During inspection, a high-resolution camera records all bond sites and wires. Dies, bond sites, wire course and component position are only a part of the inspection scope. It makes no difference whether the bonds are of copper, aluminum or gold, or whether ribbons or thick or thin wires are involved. Even thin wire bonds with a wire diameter as small as 17 µm can be reliably detected. Damage and misplaced components are also detected.

The inspection system S2088BO-II is 100 % compatible with all Viscom in-line systems and so can also be employed as a programming station. Inspection programs are quickly and easily imported to in-line-capable systems such as the S6053BO-V or S6056BO.

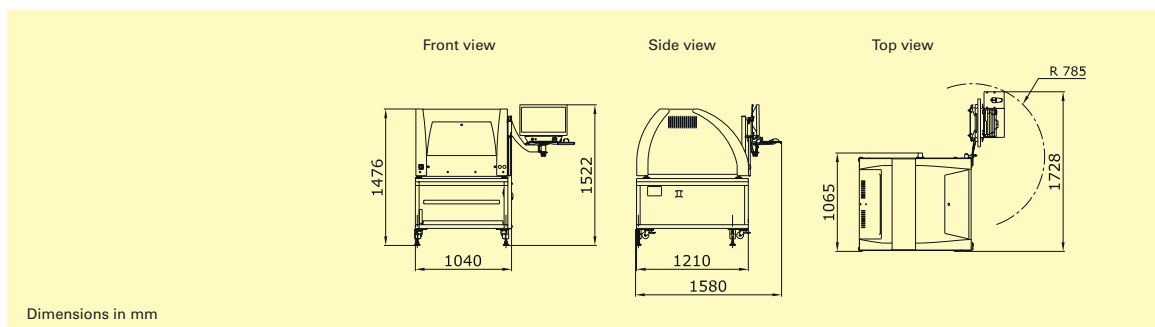
With the S2088BO-II, Viscom offers the performance capabilities of their high-end systems combined with the advantages of a compact, manually-operated desktop system.

AOI

Technical Specifications

S2088BO-II

Application	
	Ball-bond, wedge-bond, wire, die/SMD
Camera technology	
Ultra-high resolution VHR module	
Number of modules per machine	Typical 1
Number of mega pixel cameras	1
Pixel size	Typical 5 µm/pixel or 2.5 µm/pixel
	Further cameras available on request
Standard module 8M-1SRWBond	
Number of modules per machine	Typical 1
Number of mega pixel cameras	1
Pixel size	Typical 10 µm/pixel
	Further cameras available on request
Software	
User interface	Viscom EasyPro
Verification station	Viscom HARAN (integrated into system)
SPC	Viscom SPC (statistical process control), open interface (optional)
Remote diagnosis	Viscom SRC (software remote control) (optional)
Off-line programming	Viscom PST34 (external programming station) (optional)
System computer	
Operating system	Windows®
Processor	PENTIUM® processing technology
PCB handling	
Substrate dimensions	8M-1SRWBond: 600 x 457 mm (23.6" x 18") (L x W) VHR module: 152 x 127 mm (5.9" x 5") (L x W) Other sizes on request
PCB thickness	1.0 - 6.0 mm (0.04" - 0.24")
Width adjustment	Manual
Handling unit	Synchronous linear motors
PCB clamping	Mechanical, upwards
PCB contact area	2.4 mm (0.09")
Upper transport clearance	15/35 mm (0.59"/1.38") (depending on camera technology – other camera options available on request)
Lower transport clearance	60 mm (2.36")
Inspection speed	
	Up to 1000 wire-bond connections/min., depending on inspection object characteristics
Other system data	
Power requirements	110 - 240 V, 1P/N/PE, 10 A
System dimensions	1040 x 1476 x 1210 mm (40.9" x 58.1" x 47.6") (L x H x W)
Weight	Max. 140 kg (Max. 308 lbs) (without work table)



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